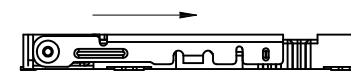


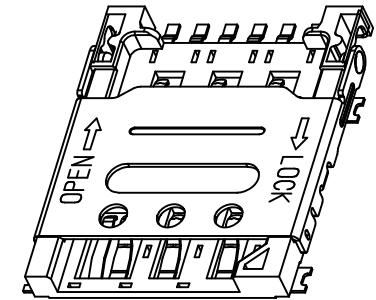
STEP 1 INSERT NANO SIM CARD



STEP 2 PUSH THE SHELL



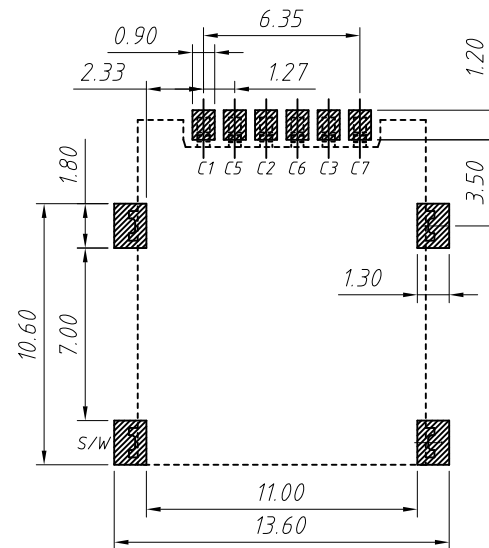
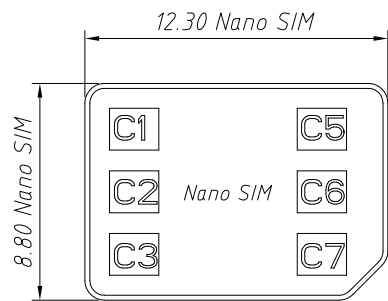
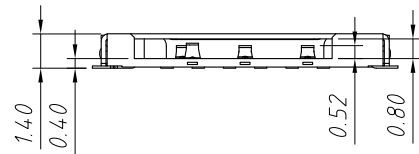
STEP 3 FINISH



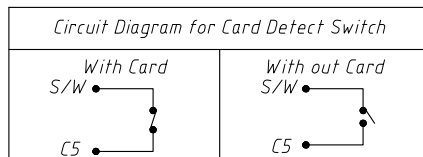
Material:
 Insulator: High Temperature Thermoplastic, UL 94 V-0.
 Contact: Copper Alloy, Plated 50u"
 Ni Overall Contact All Au 1U.
 Shell: SUS. All Ni 30U/MIN.


Electrical:
 Current Rating: 0.5A AC/DC MAX.
 Voltage Rating: 125V AC/DC
 Ambient Temperature Range: -20oC ~ +60oC
 Storage Temperature Range: -40oC ~ +70oC
 Ambient Humidity Range: 95% R.H. Max.
 Contact Resistance: 80mΩ Max.
 Insulation Resistance: 100MΩ Min./100V DC
 Mating Cycles: 5000 Insertions.
 Reflow peak temp: 260oC ±5oC, 3~5 s

Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
S/W	SWITSH PIN



PCB LAYOUT
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05



GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION	Description:
X	±0.15	X	±5°	UNITS	Nano SIM CONN;
.X	±0.03	.X	±3°	SHEET SIZE	HINGED TYPE, 6Pin, H1.4mm, with CD Pin
.XX	±0.05	.XX	±2°	KLS P/N:	L-KLS1-SIM-077A-6P-H1.4-R
Draw by:	Jenny	Date:	2018-03-10	 NingBo KLS ELECTRONIC CO.,L TD.	
Check by:		Date:	2018-03-10		
SCALE		SHEET	1 OF 1		